

L Number	Hits	Search Text	DB	Time stamp
-	97	BRUCE-MICHAEL\$.in. BRUCE-VICTORIA\$.in. GILFEATHER-GLEN\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 11:16
-	41	(BRUCE-MICHAEL\$.in. BRUCE-VICTORIA\$.in. GILFEATHER-GLEN\$.in.) and imag\$3 and remov\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 11:16
-	791	(382/145,149).CCLS.	USPAT; US-PGPUB	2004/06/24 17:49
-	1010	(inspect\$4 or fault\$3 or defect\$3 or analys\$6 or analyz\$6) same (substrate or wafer or semiconductor or semi adj conductor or IC or integrated adj circuit) with (imag\$3 or electron adj (microscop\$2) or SEM or camera or CCD or video) with (remov\$3 or FIB or ion near beam or etch\$3 or CMP or mechanical\$2 near polish\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/25 10:26
-	119	(inspect\$4 or fault\$3 or defect\$3 or analys\$6 or analyz\$6) with (imag\$3 or electron adj (microscop\$2) or SEM or camera or CCD or video) with (remov\$3) near (substrate or layer or wafer or semiconductor or semi adj conductor or IC or integrated adj circuit or die or dice) JP-01119037-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/25 15:37
-	2		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 15:44
-	23	382/141-151.ccls. and (remov\$3 or FIB or (ion or electron or e) near beam or etch\$3 or CMP or (mechanical\$2 near polish\$3) or cross adj section\$3) with (layer or substrate or wafer or die or dice or semiconductor or semi adj conductor) with (simultaneous\$2 or concurrent\$2 or "same" adj time or "in" adj process)	USPAT; US-PGPUB	2004/06/25 14:51
-	101	((three or "3") adj dimension\$4 or "3" adj D or 3D) same (remov\$3 or FIB or ion near beam or etch\$3 or CMP or mechanical\$2 near polish\$3 or cross adj section\$3) with (substrate or wafer or semiconductor or semi adj conductor or IC or integrated adj circuit) with (simultaneous\$2 or concurrent\$2 or "same" adj time)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/25 14:52
-	138	(imag\$3 or electron adj (microscop\$2) or SEM or camera or CCD or video) with (remov\$3 or FIB or ion near beam or CMP or mechanical\$2 near polish\$3 or cross adj section\$3) with (substrate or wafer or semiconductor or semi adj conductor or IC or integrated adj circuit) with (simultaneous\$2 or concurrent\$2 or "same" adj time)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/25 14:53

-	27	(inspect\$4 or fault\$3 or defect\$3 or analys\$6 or analyz\$6) same (substrate or wafer or semiconductor or semi adj conductor or IC or integrated adj circuit) same (imag\$3 or electron adj (microscop\$2) or SEM or camera or CCD or video) with (remov\$3 or FIB or ion near beam or etch\$3 or CMP or mechanical\$2 near polish\$3 or cross adj section\$3) with (simultaneous\$2 or concurrent\$2 or "same" adj time)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/25 14:54
-	34	(inspect\$4 or fault\$3 or defect\$3 or analys\$6 or analyz\$6) near (locat\$3 or caus\$3 or localiz\$6) same (imag\$3 or electron adj (microscop\$2) or SEM or camera or CCD or video or (three or "3") adj dimension\$4 or "3" adj D or 3D) same (remov\$3 or FIB or ion near beam or CMP or mechanical\$2 near polish\$3 or cross adj section\$3 or slic\$3 or dicing or cut or cutting or cleav\$3) near (substrate or layer or wafer or semiconductor or semi adj conductor or IC or integrated adj circuit or die or dice\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/25 15:58
-	1	TW-421841-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 15:45
-	1	TW-373282-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 15:45